

Title (en)  
METHOD FOR SUPPRESSING INCREASE IN ZINC CONCENTRATION IN PLATING SOLUTION, AND METHOD FOR PRODUCING ZINC-BASED PLATING MEMBER

Title (de)  
VERFAHREN ZUR UNTERDRÜCKUNG DER ERHÖHUNG DER ZINKKONZENTRATION IN EINER PLATTIERUNGSLÖSUNG UND VERFAHREN ZUR HERSTELLUNG EINER BESCHICHTUNG AUF ZINKBASIS

Title (fr)  
PROCÉDÉ DE SUPPRESSION D'AUGMENTATION DE LA CONCENTRATION EN ZINC DANS UNE SOLUTION DE PLACAGE, ET PROCÉDÉ DE PRODUCTION D'ÉLÉMENT DE PLACAGE À BASE DE ZINC

Publication  
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Application  
**EP 20886179 A 20200821**

Priority  
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Abstract (en)  
Provided is a method for suppressing an increase in the zinc concentration of a plating solution when a zinc alloy plating member using nickel as an alloy element is manufactured using a zinc alloy plating apparatus. The plating apparatus includes: a plating tank capable of accommodating the plating solution which is acidic; a first diaphragm tank which is capable of accommodating a first electrolytic solution and has a first diaphragm composed of a cation exchange membrane; a cathode holding member for cathode-electrolyzing a member to be plated that is in contact with the plating solution inside the plating tank during use; a first anode holding member for anode-electrolyzing a soluble zinc-containing member that is in contact with the first electrolytic solution inside the first diaphragm tank during use; the soluble zinc-containing member held by the first anode holding member; a soluble metal-containing member containing the nickel which is the alloy element; and a second anode holding member for anode-electrolyzing the soluble metal-containing member. The first diaphragm tank is arranged in a manner that the first electrolytic solution is in contact with one surface of the first diaphragm and the plating solution is in contact with the other surface of the first diaphragm during use.

IPC 8 full level  
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